



DISCRETE POWER DIODES and THYRISTORS

DATA BOOK



ST303C..L SERIES

INVERTER GRADE THYRISTORS

Hockey Puk Version

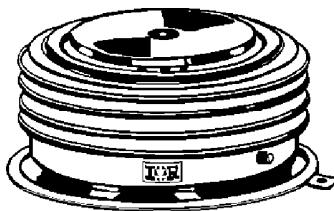
Features

- Metal case with ceramic insulator
- International standard case TO-200AC (B-PUK)
- All diffused design
- Center amplifying gate
- Guaranteed high dV/dt
- Guaranteed high dI/dt
- High surge current capability
- Low thermal impedance
- High speed performance

515A

Typical Applications

- Inverters
- Choppers
- Induction heating
- All types of force-commutated converters



case style TO-200AC (B-PUK)

Major Ratings and Characteristics

Parameters	ST303C..L	Units
$I_{T(AV)}$	515	A
	@ T_{hs}	°C
$I_{T(RMS)}$	995	A
	@ T_{hs}	°C
I_{TSM}	@ 50Hz	A
	@ 60Hz	A
I^2t	@ 50Hz	KA ² s
	@ 60Hz	KA ² s
V_{DRM}/V_{RRM}	400 to 1200	V
t_q range (*)	10 to 30	μs
T_J	- 40 to 125	°C

(*) $t_q = 10$ to $20\mu s$ for 400 to 800V devices
 $t_q = 15$ to $30\mu s$ for 1000 to 1200V devices

ST303C..L Series

ELECTRICAL SPECIFICATIONS

Voltage Ratings

Type number	Voltage Code	V_{DRM}/V_{RRM} , maximum repetitive peak voltage V	V_{RSM} , maximum non-repetitive peak voltage V	I_{DRM}/I_{RRM} max. @ $T_J = T_{J\max}$ mA
ST303C..L	04	400	500	50
	08	800	900	
	10	1000	1100	
	12	1200	1300	

Current Carrying Capability

Frequency				Units	
50Hz	1130	950	1800	1540	A
400Hz	1010	820	1850	1570	
1000Hz	680	530	1560	1300	
2500Hz	230	140	690	510	
Recovery voltage V_r	50	50	50	50	V
Voltage before turn-on V_d	V_{DRM}		V_{DRM}		
Rise of on-state current di/dt	50	50	-	-	A/ μ s
Heatsink temperature	40	55	40	55	°C
Equivalent values for RC circuit	$10\Omega / 0.47\mu F$		$10\Omega / 0.47\mu F$		

On-state Conduction

Parameter	ST303C..L	Units	Conditions			
$I_{T(AV)}$ Max. average on-state current @ Heatsink temperature	515 (190)	A	180° conduction, half sine wave double side (single side) cooled			
	55 (85)	°C				
$I_{T(RMS)}$ Max. RMS on-state current	995		DC @ 25°C heatsink temperature double side cooled			
I_{TSM} Max. peak, one half cycle, non-repetitive surge current	7950	A	t = 10ms	No voltage reapplied	Sinusoidal half wave, Initial $T_J = T_{J\max}$	
	8320		t = 8.3ms			
	6690		t = 10ms	100% V_{RRM} reapplied		
	7000		t = 8.3ms			
I^2t Maximum I^2t for fusing	316	KA ² s	t = 10ms	No voltage reapplied		
	289		t = 8.3ms			
	224		t = 10ms	100% V_{RRM} reapplied		
	204		t = 8.3ms			
$I^{2\sqrt{t}}$ Maximum $I^{2\sqrt{t}}$ for fusing	3160	KA ² /s	t = 0.1 to 10ms, no voltage reapplied			

ST303C..L Series

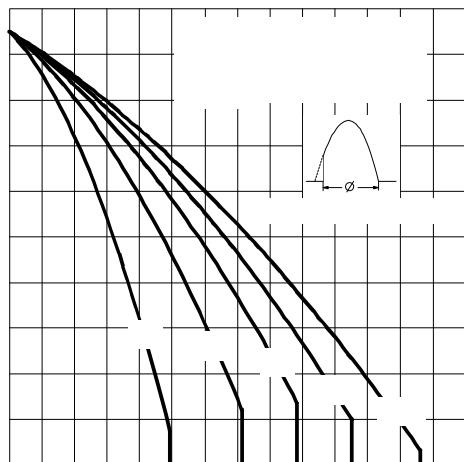


Fig. 3 - Current Ratings Characteristics

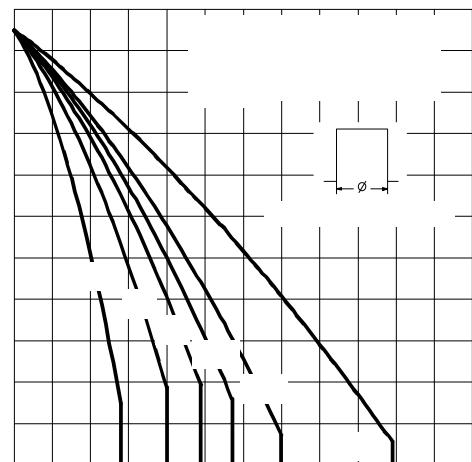


Fig. 4 - Current Ratings Characteristics

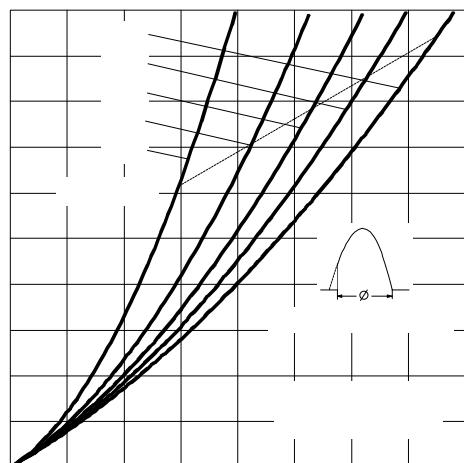


Fig. 5 - On-state Power Loss Characteristics

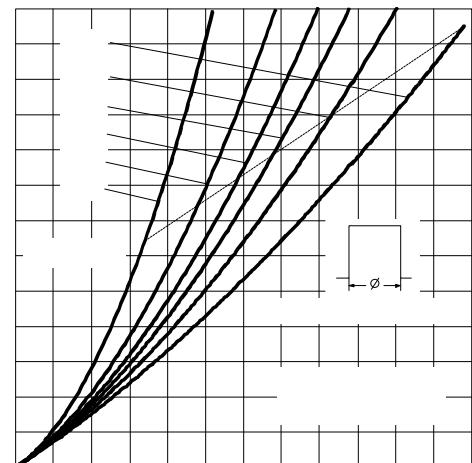


Fig. 6 - On-state Power Loss Characteristics

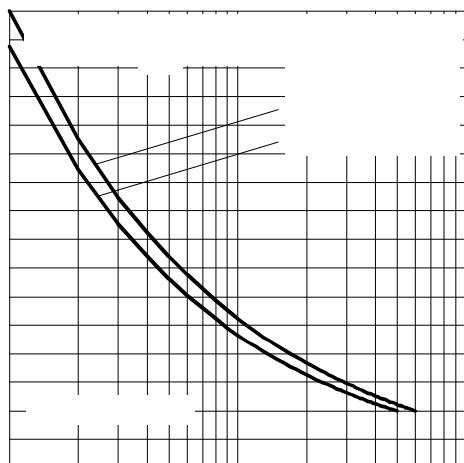


Fig. 7 - Maximum Non-repetitive Surge Current

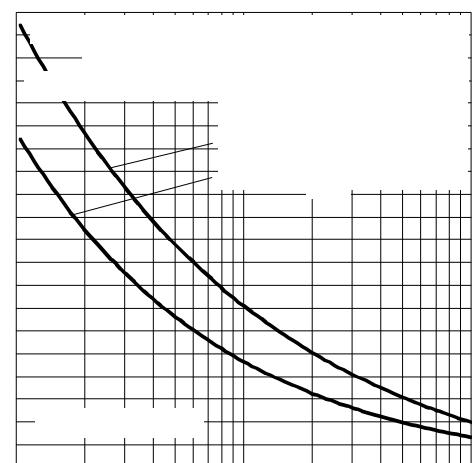


Fig. 8 - Maximum Non-repetitive Surge Current

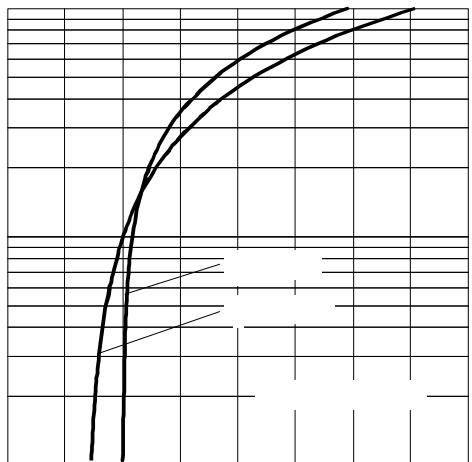


Fig. 9 - On-state Voltage Drop Characteristics

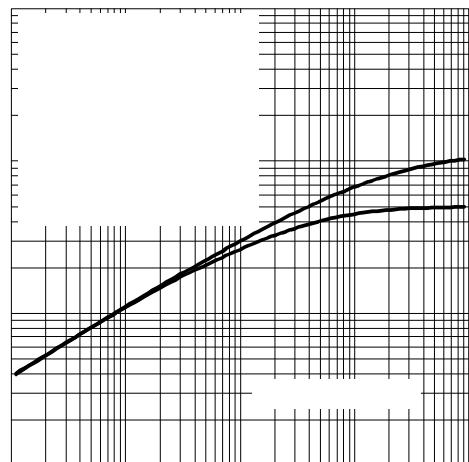


Fig. 10 - Thermal Impedance Z_{thJ-hs} Characteristics

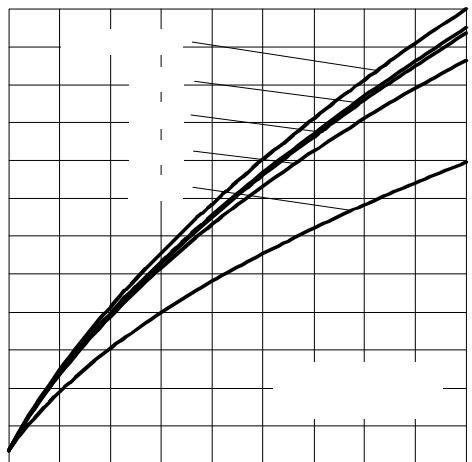


Fig. 11 - Reverse Recovered Charge Characteristics

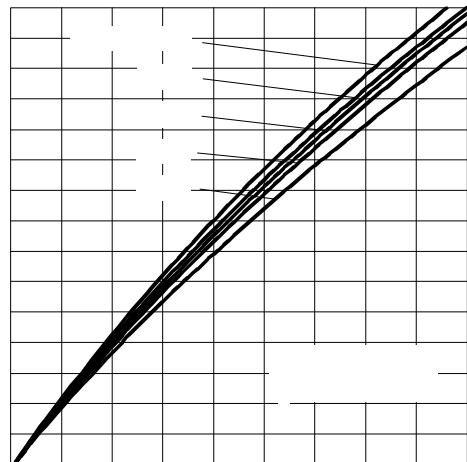


Fig. 12 - Reverse Recovery Current Characteristics

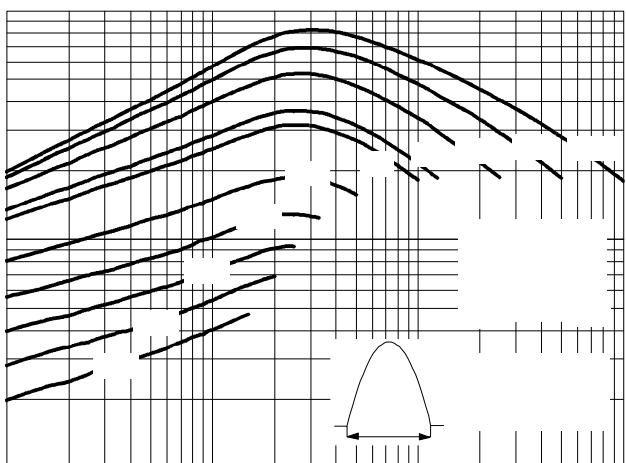
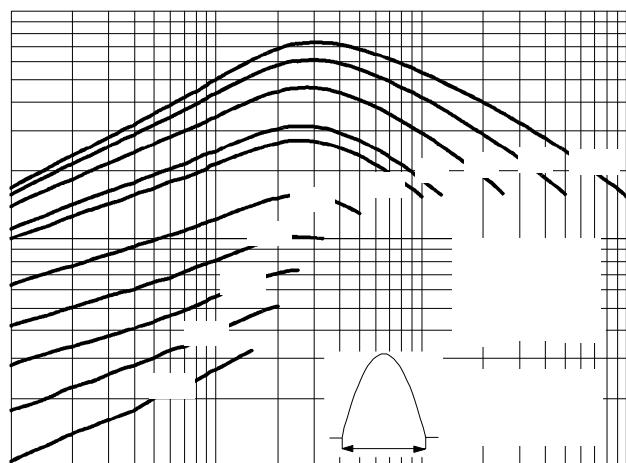


Fig. 13 - Frequency Characteristics



ST303C..L Series

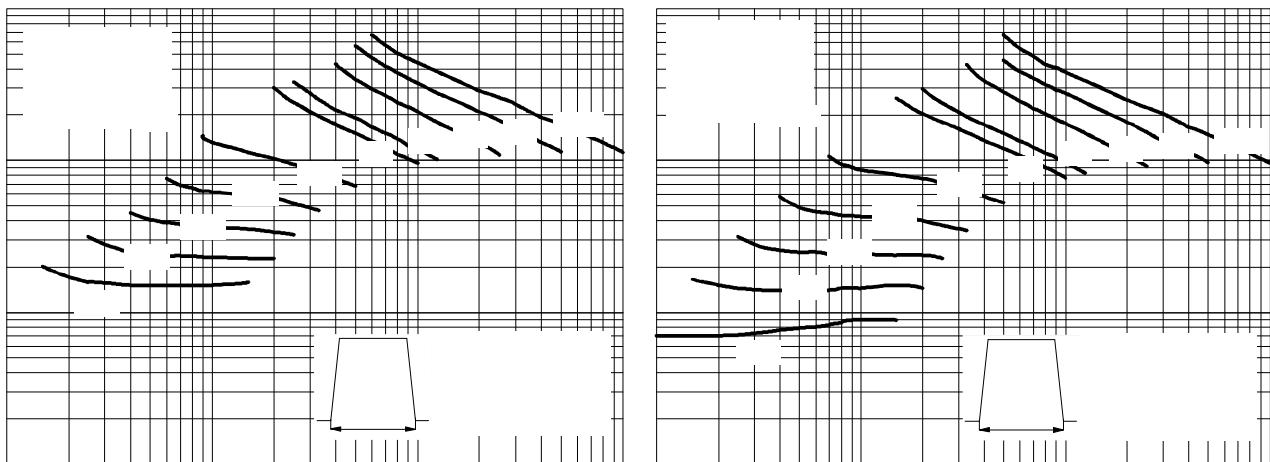


Fig. 14 - Frequency Characteristics

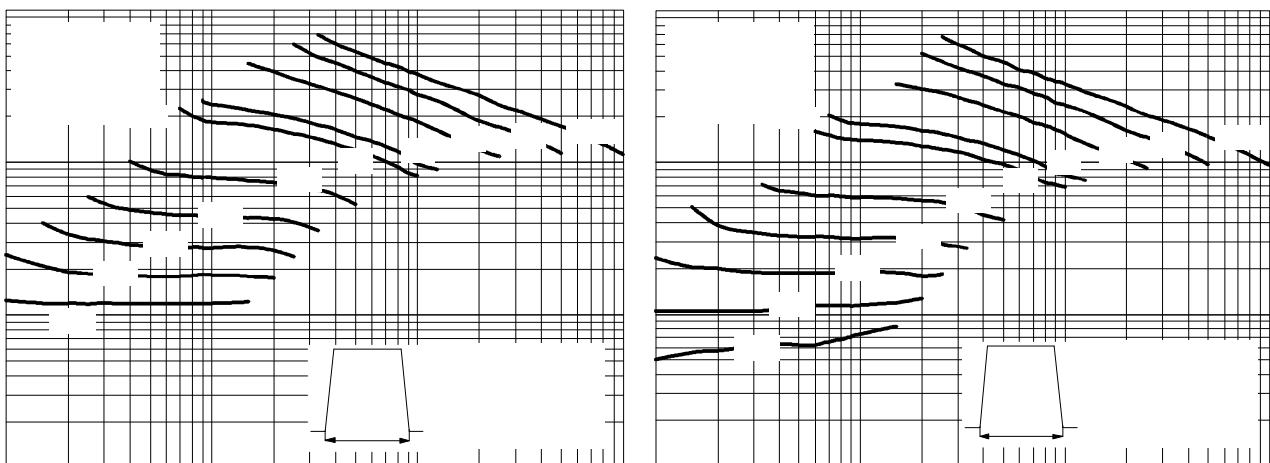


Fig. 15 - Frequency Characteristics

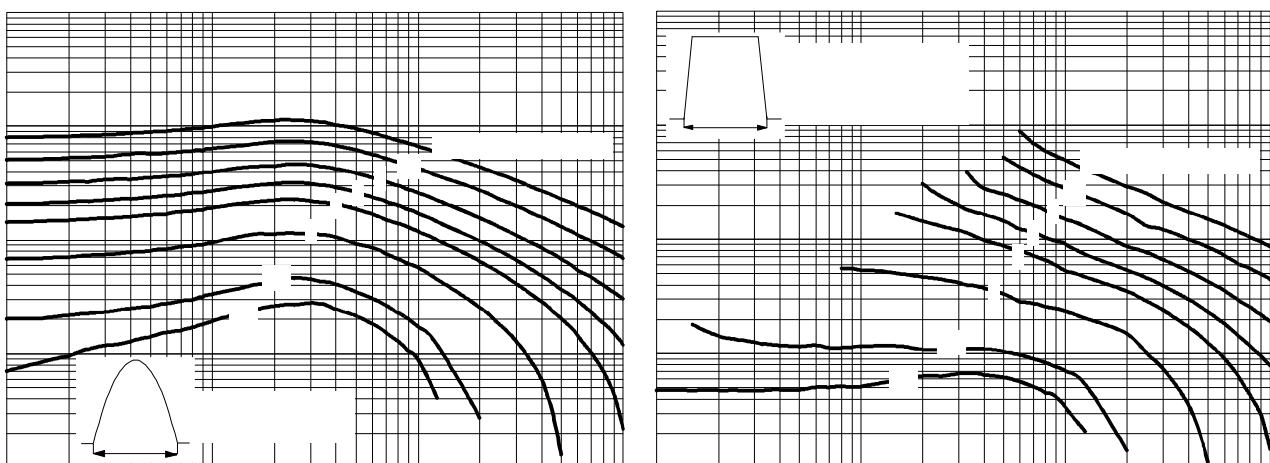


Fig. 16 - Maximum On-state Energy Power Loss Characteristics

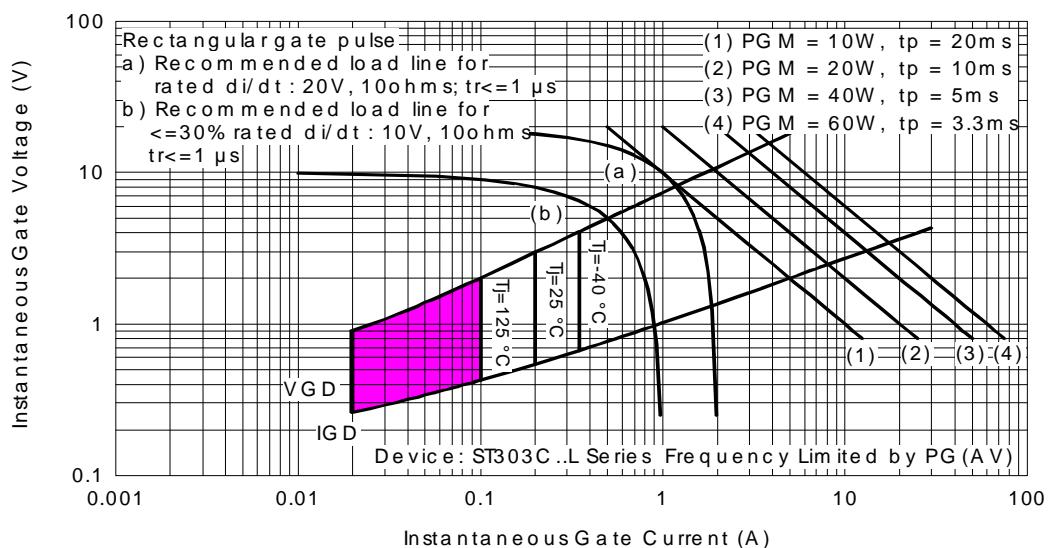


Fig. 17 - Gate Characteristics

On-state Conduction

Parameter	ST303C..L	Units	Conditions
V_{TM}	Max. peak on-state voltage	V	$I_{TM} = 1255A, T_J = T_J \text{ max}, t_p = 10\text{ms sine wave pulse}$
$V_{T(TO)1}$	Low level value of threshold voltage		$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
$V_{T(TO)2}$	High level value of threshold voltage		$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
r_{t1}	Low level value of forward slope resistance	$\text{m}\Omega$	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}, T_J = T_J \text{ max.})$
r_{t2}	High level value of forward slope resistance		$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
I_H	Maximum holding current	mA	$T_J = 25^\circ\text{C}, I_T > 30\text{A}$
I_L	Typical latching current		$T_J = 25^\circ\text{C}, V_A = 12\text{V}, R_a = 6\Omega, I_G = 1\text{A}$

Switching

Parameter	ST303C..L	Units	Conditions
di/dt	Max. non-repetitive rate of rise of turned-on current	A/ μs	$T_J = T_J \text{ max}, V_{DRM} = \text{rated } V_{DRM}$ $I_{TM} = 2 \times di/dt$
t_d	Typical delay time	μs	$T_J = 25^\circ\text{C}, V_{DM} = \text{rated } V_{DRM}, I_{TM} = 50\text{A DC}, t_p = 1\mu\text{s}$ Resistive load Gate pulse: 10V, 5Ω source
t_q	Max. turn-off time (*)		$T_J = T_J \text{ max}, I_{TM} = 550\text{A}, \text{commutating } di/dt = 40\text{A}/\mu\text{s}$ $V_R = 50\text{V}, t_p = 500\mu\text{s}, dv/dt: \text{see table in device code}$

(*) $t_q = 10$ to $20\mu\text{s}$ for 400 to 800V devices; $t_q = 15$ to $30\mu\text{s}$ for 1000 to 1200V devices.

Blocking

Parameter	ST303C..L	Units	Conditions
dv/dt	Maximum critical rate of rise of off-state voltage	V/ μs	$T_J = T_J \text{ max. linear to } 80\% V_{DRM}, \text{higher value available on request}$
I_{RRM} I_{DRM}	Max. peak reverse and off-state leakage current	mA	$T_J = T_J \text{ max, rated } V_{DRM}/V_{RRM} \text{ applied}$

Triggering

Parameter	ST303C..L	Units	Conditions
P_{GM}	Maximum peak gate power	W	$T_J = T_J \text{ max, } f = 50\text{Hz, d\% = 50}$
$P_{G(AV)}$	Maximum average gate power		
I_{GM}	Max. peak positive gate current	A	$T_J = T_J \text{ max, } t_p \leq 5\text{ms}$
$+V_{GM}$	Maximum peak positive gate voltage		
$-V_{GM}$	Maximum peak negative gate voltage	V	$T_J = T_J \text{ max, } t_p \leq 5\text{ms}$
I_{GT}	Max. DC gate current required to trigger	mA	$T_J = 25^\circ\text{C}, V_A = 12\text{V}, R_a = 6\Omega$
V_{GT}	Max. DC gate voltage required to trigger		
I_{GD}	Max. DC gate current not to trigger	mA	$T_J = T_J \text{ max, rated } V_{DRM} \text{ applied}$
V_{GD}	Max. DC gate voltage not to trigger		

ST303C..L Series

Thermal and Mechanical Specification

Parameter	ST303C..L	Units	Conditions
T_J	Max. operating temperature range	-40 to 125	°C
T_{stg}	Max. storage temperature range	-40 to 150	
R_{thJ-hs}	Max. thermal resistance, junction to heatsink	0.11 0.05	K/W
R_{thC-hs}	Max. thermal resistance, case to heatsink	0.011 0.005	
F	Mounting force, ± 10%	9800 (1000)	N (Kg)
wt	Approximate weight	250	g
Case style	TO - 200AC (B-PUK)	See Outline Table	

ΔR_{thJ-hs} Conduction

(The following table shows the increment of thermal resistance R_{thJ-hs} when devices operate at different conduction angles than DC)

Conduction angle	Sinusoidal conduction		Rectangular conduction		Units	Conditions
	Single Side	Double Side	Single Side	Double Side		
180°	0.012	0.010	0.008	0.008	K/W	$T_J = T_{J \text{ max.}}$
120°	0.014	0.015	0.014	0.014		
90°	0.018	0.018	0.019	0.019		
60°	0.026	0.027	0.027	0.028		
30°	0.045	0.046	0.046	0.046		

Ordering Information Table

Device Code	ST	30	3	C	12	L	H	K	1	
	1	2	3	4	5	6	7	8	9	10
1	- Thyristor									
2	- Essential part number									
3	- 3 = Fast turn off									
4	- C = Ceramic Puk									
5	- Voltage code: Code x 100 = V_{RRM} (See Voltage Rating Table)									
6	- L = Puk Case TO-200AC (B-PUK)									
7	- Reapplied dv/dt code (for t_q test condition)									
8	- t_q code _____									
9	- 0 = Eyelet term. (Gate and Aux. Cathode Unsoldered Leads)									
	1 = Fast-on term. (Gate and Aux. Cathode Unsoldered Leads)									
	2 = Eyelet term. (Gate and Aux. Cathode Soldered Leads)									
	3 = Fast-on term. (Gate and Aux. Cathode Soldered Leads)									
10	- Critical dv/dt:									
	None = 500V/μsec (Standard value)									
	L = 1000V/μsec (Special selection)									

dv/dt - t_q combinations available						
t_q (μs)	10	CN	DN	EN	FN *	HN
up to 800V	12	CM	DM	EM	FM	HM
	15	CL	DL	EL	FL *	HL
	20	CK	DK	EK	FK *	HK

t_q (μs)	15	CL	--	--	--	--
only for 1000/1200V	18	CP	DP	--	--	--
	20	CK	DK	EK	FK *	HK
	25	CJ	DJ	EJ	FJ *	HJ
	30	--	DH	EH	FH	HH

*Standard part number.
All other types available only on request.

Outline Table

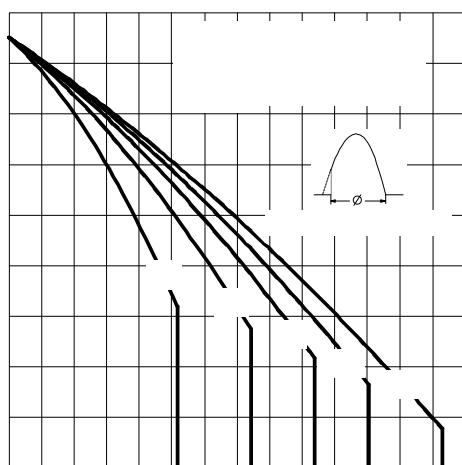
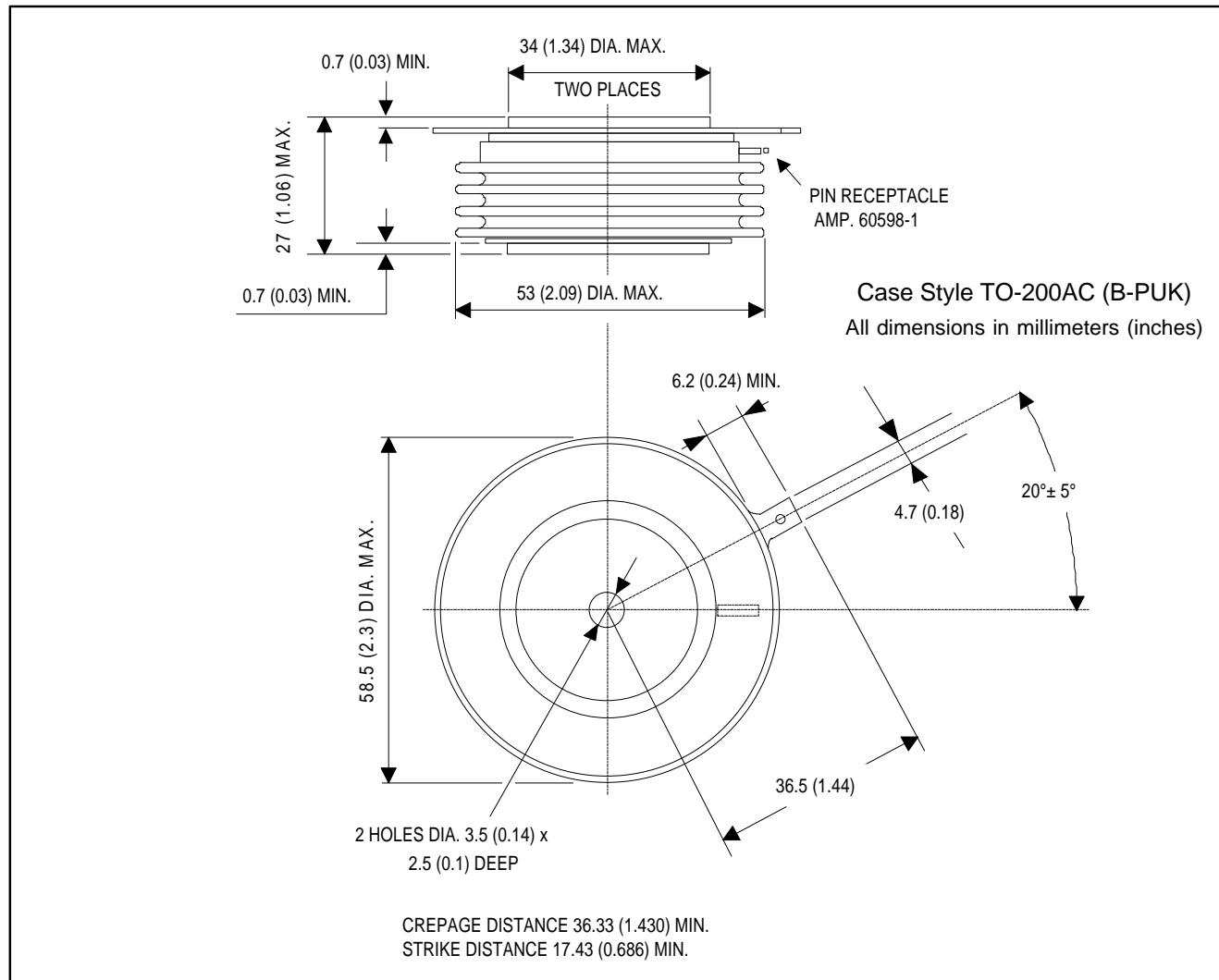


Fig. 1 - Current Ratings Characteristics

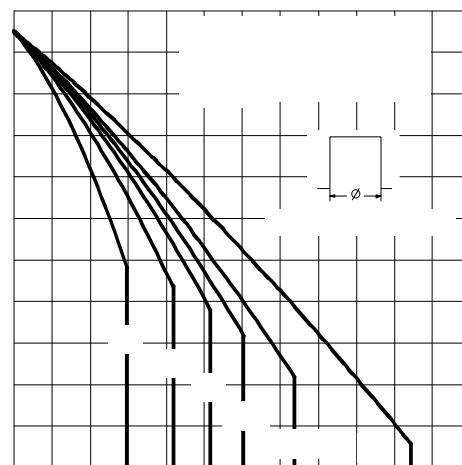


Fig. 2 - Current Ratings Characteristics